

In the Claims:

1       Claim 26 (currently amended) An electronic package comprising:  
2            a first circuitized substrate having at least one conductive aperture therein having  
3            an external surface;  
4            a second circuitized substrate having at least one conductive aperture therein  
5            having an external surface, said first and second circuitized substrates aligned such that  
6            said at least one conductive aperture of said first circuitized substrate is substantially  
7            aligned with said at least one conductive aperture of said second circuitized substrate, said  
8            at least one conductive aperture of said first circuitized substrate and said at least one  
9            conductive aperture of said second circuitized substrate including a conductive metallic  
10          layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder  
11          and alloys thereof; and  
12            at least one high melt solder alloy member having a melting point greater than  
13          about 183° Celsius with said solder member including a first contact portion extending  
14          from said external surface of said conductive aperture of said first circuitized substrate,  
15          said first contact portion including a cross-sectional configuration that is substantially  
16          round, oval or ellipsoidal, and a second contact portion extending substantially within both  
17          of said aligned conductive apertures of said first and second circuitized substrates to at  
18          least said external surface of said conductive aperture of said second circuitized substrate  
19          to secure said circuitized substrates together.

Claim 27 (canceled)

1       Claim 28 (previously amended) The electronic package of Claim 26 wherein said  
2       conductive metallic layer is copper including a protective layer thereon, said protective  
3       layer selected from the group consisting of benzotriazole, chlorite, and immersion tin.

Claim 29 (canceled)

1       Claim 30 (currently amended) The electronic package of Claim 26 29 wherein said  
2       high melt solder alloy member is comprised of metallic material, said metallic material is  
3       selected from the group consisting of tin, lead, gold, silver, antimony, and combinations  
4       thereof.

Claim 31 (canceled)

1       Claim 32 (new) An electronic package comprising:  
2            a first circuitized substrate having at least one conductive aperture therein having  
3            an external surface, said first circuitized substrate comprised of material selected from the  
4            group consisting of polyimide, polytetrafluoroethylene and epoxy glass cloth;  
5            a second circuitized substrate having at least one conductive aperture therein  
6            having an external surface, said second circuitized substrate comprised of material selected  
7            from the group consisting of polyimide, polytetrafluoroethylene and epoxy glass cloth,  
8            said first and second circuitized substrates aligned such that said at least one conductive  
9            aperture of said first circuitized substrate is substantially aligned with said at least one  
10          conductive aperture of said second circuitized substrate, said at least one conductive

11 aperture of said first circuitized substrate and said at least one conductive aperture of said  
12 second circuitized substrate including a conductive metallic layer thereon selected from the  
13 group consisting of copper, nickel, gold, chromium, solder and alloys thereof; and  
14 at least one solder member including a first contact portion extending from said  
15 external surface of said conductive aperture of said first circuitized substrate, said first  
16 contact portion including a cross-sectional configuration that is substantially round, oval  
17 or ellipsoidal, and a second contact portion extending substantially within both of said  
18 aligned conductive apertures of said first and second circuitized substrates to at least said  
19 external surface of said conductive aperture of said second circuitized substrate to secure  
20 said circuitized substrates together.

1 Claim 33 (new) An electronic package comprising:  
2 a first circuitized substrate having at least one conductive aperture therein having  
3 an external surface;  
4 a second circuitized substrate having at least one conductive aperture therein  
5 having an external surface, said first and second circuitized substrates aligned such that  
6 said at least one conductive aperture of said first circuitized substrate is substantially  
7 aligned with said at least one conductive aperture of said second circuitized substrate, said  
8 at least one conductive aperture of said first circuitized substrate and said at least one  
9 conductive aperture of said second circuitized substrate including a conductive metallic  
10 layer thereon selected from the group consisting of copper, nickel, gold, chromium, solder  
11 and alloys thereof; and

12 at least one solder member including a first contact portion extending from said  
13 external surface of said conductive aperture of said first circuitized substrate to form a  
14 connection to a printed circuit board, said first contact portion including a cross-sectional  
15 configuration that is substantially round, oval or ellipsoidal, and a second contact portion  
16 extending substantially within both of said aligned conductive apertures of said first and  
17 second circuitized substrates to at least said external surface of said conductive aperture of  
18 said second circuitized substrate to secure said circuitized substrates together.